

# [PACKAGE STRUCTURE COMPATIBLE WITH COOLING SYSTEM]

## Abstract

The present invention relates to a package structure compatible with a cooling system, the package structure comprising a carrier, a chip, a mold compound and a cooling tubule that can be connected to a cooling system. The chip is arranged on the carrier and electrically connected to the carrier, while the mold compound covers the chip and one surface of the carrier. The cooling tubule is disposed either within the mold compound or on an outer surface of the mold compound. The cooling tubule is connected to a cooling tubing of the cooling system and a fluid driven by a pump circulates in the cooling tubing and the cooling tubule for heat dissipation.